PATENT COOPERATION TREATY



PCT

INTERNATIONAL PRELIMINARY REPORT ON PATENTABILITY (Chapter II of the Patent Cooperation Treaty)

(PCT Article 36 and Rule 70)

Applicant's or agent's file reference FP-8522PCT	FOR FURTHER ACTI	ON	See Form PCT/IPEA/416		
International application No.	International filing date (lay/month/year)	Priority date (day/month/year)		
PCT/JP2003/015928	12 December 2003		13 December 2002 (13.12.2002)		
International Patent Classification (IPC) or r C08L 79/08, B32B 27/34, C23C	lational classification and II				
Applicant	KANEKA CORP	ORATION			
This report is the international preli- Authority under Article 35 and trans	minary examination report, smitted to the applicant acc	established by this cording to Article 3	s International Preliminary Examining 6.		
2. This REPORT consists of a total or		cluding this cover	sheet.		
This report is also accompanied by	ANNEXES, comprising:				
a. (sent to the applicant and to the International Bureau) a total of sheets, as follows:					
sheets of the description, claims and/or drawings which have been amended and are the basis of this report and/or sheets containing rectifications authorized by this Authority (see Rule 70.16 and Section 607 of the Administrative Instructions).					
sheets which supersede earlier sheets, but which this Authority considers contain an amendment that goes beyond the disclosure in the international application as filed, as indicated in item 4 of Box No. I and the Supplemental Box.					
	indicated in the Suppleme		type and number of electronic carrier(s)) ing and/or tables related thereto, in computer to Sequence Listing (see Section 802 of the		
This report contains indications re		ıs:			
Box No. I Basis of the	report				
Box No. II Priority					
Box No. III Non-establishment of opinion with regard to novelty, inventive step and industrial applicability					
Box No. IV Lack of unity of invention					
Box No. V Reasoned statement under Article 35(2) with regard to novelty, inventive step or industrial applicability; citations and explanations supporting such statement					
Box No. VI Certain documents cited					
Box No. VII Certain defects in the international application					
Box No. VIII Certain observations on the international application					
Date of submission of the demand		Date of completion	on of this report		
09 April 2004 (09.0)4.2004)	15	September 2004 (15.09.2004)		
Name and mailing address of the IPEA/	JP	Authorized office	er -		
Recsimile No.		Telephone No.			

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International application No.

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Listing.
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	tion 4
Box No. V	Reasoned statement under Article 35(2) with regard to novelty, inventive step or industrial applicability;
DUA INO. V	citations and explanations supporting such statement
	Citations and explanations outperson

Claims	7-11	YES
Claims	1-6, 12-21	ио
Claims		YES
Claims	1-21	NO
Claims	1-21	YES
		МО
	Claims Claims Claims Claims	Claims 1-6, 12-21 Claims 1-21

2. Citations and explanations (Rule 70.7)

Document 1: US, 6286207, B1 (NEC Corporation), September 11, 2001 (09.11.01), Full text & JP, 2000-17444, A

Document 2: JP, 2001-332864, A (Sumitomo Metal (SMI) Electronics Devices Inc.), November 30, 2001 (11.30.01), Claims, Paragraphs 0004-0005, 0007 and 0009-0016

Document 3: JP, 2002-307608, A (Kaneka Corporation), October 23, 2002 (10.23.02), Claims, Paragraphs 0001, 0026-0032, 0038-0039, 0041 and 0048-0066, Embodiment, Fig. 1-Fig. 2F

Claims 1-5

The inventions relating to claims 1-5 are described in documents 1-2 cited in the ISR; therefore, they do not appear to be novel or involve an inventive step.

Documents 1-2 describe a polyimide resin material wherein, in consideration of bonding strength with an electroless plating film, a surface is subject to treatment such as roughening. Also, they describe the point of keeping surface roughness low in consideration of the fineness of wiring and other factors. On the other hand, as described in document 3 (embodiments), sufficient bonding strength between an electroless plating film and polyimide resin material is normally at least 5N/cm. Thus, it cannot be said that there is any difference in bonding strength between the inventions relating to claims 1-4 and the inventions described in documents 1-2.

(As described in document 3 (paragraphs 0038-0039), the various surface treatment methods of a polyimide resin material used in the present invention are well known to a party skilled in the art.)

Claim 6

The invention relating to claim 6 is described in documents 1-2 cited in the ISR; therefore, it does not appear to be novel or involve an inventive step. As can be seen from the description of document 3, the polyimide described in claim 6 is commonly used in the relevant technical fields.

Claims 7-11

The inventions relating to claims 7-11 do not appear to involve an inventive step based on documents 1-3 cited in the ISR.

As described in document 3, in a printed wiring board, using a multilayer body comprising a layer made of an electroless plating film and polyimide film and an adhesion layer made of a thermosetting resin including a polyimide resin is commonly carried out by a party skilled in the art.

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Supplemental Box

In case the space in any of the preceding boxes is not sufficient. Continuation of Box V:

Claims 12-15

The inventions relating to claims 12-15 do not appear to be novel or involve an inventive step based on documents 1-2 cited in the ISR.

From the standpoint of technical concepts, it cannot be said that there is any difference in surface roughness between the inventions relating to claims 12-15 and the inventions described in documents 1-2.

Claims 16-21

The inventions relating to claims 16-21 do not appear to be novel or involve an inventive step based on documents 1-2 cited in the ISR. Regarding a manufacturing method of a printed wiring board, the inventions relating to claims 16-21 are merely using an ordinary method.